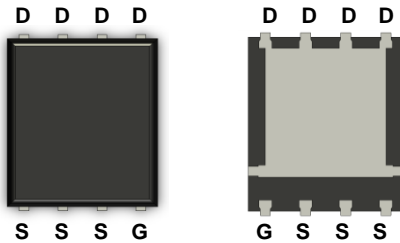


### General Description

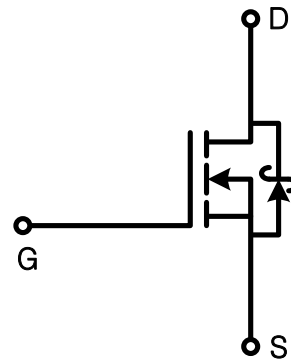
The MDU1532S uses advanced MagnaChip's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance and excellent quality. MDU1532S is suitable device for DC/DC Converter and general purpose applications.

### Features

- $V_{DS} = 30V$
- $I_D = 32A @V_{GS} = 10V$
- $R_{DS(ON)} < 4.2 m\Omega @V_{GS} = 10V$   
 $< 5.3 m\Omega @V_{GS} = 4.5V$
- 100% UIL Tested
- 100% Rg Tested
- SBD Built In



PDFN56



### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DSS}$	30	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>(1)</sup>	$T_C=25^\circ C$ (Silicon Limited)	$I_D$	105	A
	$T_C=25^\circ C$ (Package Limited)		32	
	$T_A=25^\circ C$		29.5	
	$T_A=70^\circ C$		23.7	
Pulsed Drain Current		$I_{DM}$	128	
Power Dissipation	$T_C=25^\circ C$	$P_D$	69	W
	$T_A=25^\circ C$		5.5	
Single Pulse Avalanche Energy <sup>(2)</sup>		$E_{AS}$	20	mJ
Junction and Storage Temperature Range		$T_J, T_{stg}$	-55~150	°C

### Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient <sup>(1)</sup>	$R_{\theta JA}$	22.7	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.8	

## Ordering Information

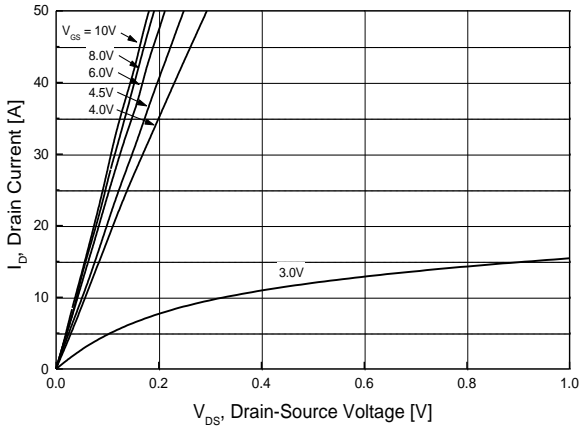
Part Number	Temp. Range	Package	Packing	RoHS Status
MDU1532SURH	-55~150°C	PDFN56	Tape & Reel	Halogen Free

## Electrical Characteristics (T<sub>J</sub> = 25°C)

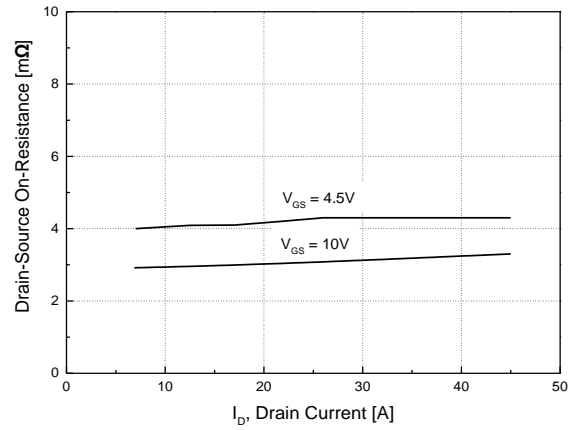
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> = 10mA, V <sub>GS</sub> = 0V	30	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.8	3.0	
Drain Cut-Off Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V	-	-	0.5	mA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Drain-Source ON Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	3.6	4.2	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	4.5	5.3	
Forward Trans conductance	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	-	85	-	S
<b>Dynamic Characteristics</b>						
Total Gate Charge	Q <sub>g(10V)</sub>	V <sub>DD</sub> = 15V, I <sub>D</sub> = 20A, V <sub>GS</sub> = 10V	-	42.1	58	nC
Total Gate Charge	Q <sub>g(4.5V)</sub>		-	18.0	25	
Gate-Source Charge	Q <sub>gs</sub>		-	8.4	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	3.6	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	2900	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	89	-	
Output Capacitance	C <sub>oss</sub>		-	910	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15.0V, I <sub>D</sub> = 20A, R <sub>G</sub> = 3Ω	-	14.4	-	ns
Rise Time	t <sub>r</sub>		-	12.3	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	43.2	-	
Fall Time	t <sub>f</sub>		-	7.1	-	
Gate Resistance	R <sub>g</sub>	f=1 MHz	0.5	1.1	1.5	Ω
<b>Drain-Source Body Diode Characteristics</b>						
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	0.4	1.0	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A, di/dt = 100A/μs	-	43	-	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	48	-	nC

Note :

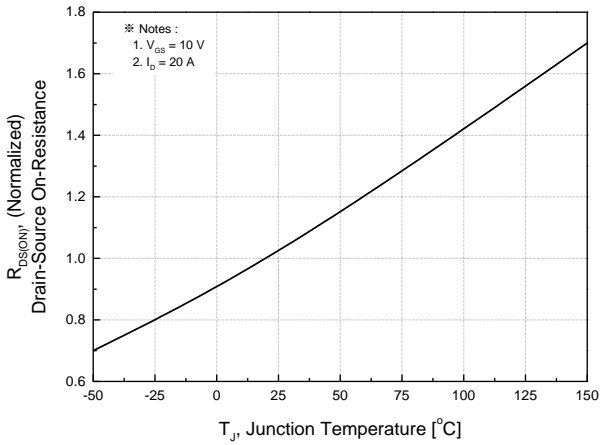
- Surface mounted FR-4 board by JEDEC (jesd51-7). Continuous current at T<sub>C</sub>=25°C is silicon limited
- E<sub>AS</sub> is tested at starting T<sub>J</sub> = 25°C, L = 0.1mH, I<sub>AS</sub> = 20 A, V<sub>DD</sub> = 27V, V<sub>GS</sub> = 10V.



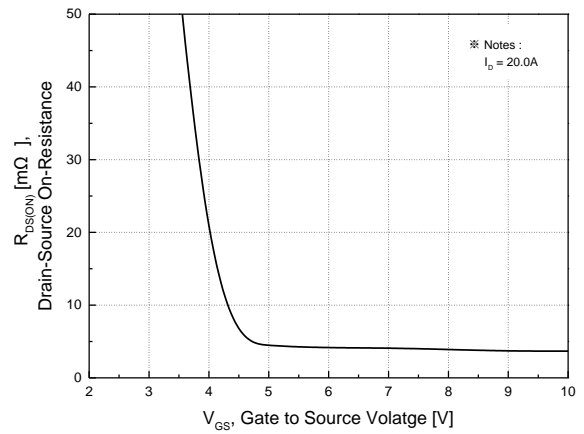
**Fig.1 On-Region Characteristics**



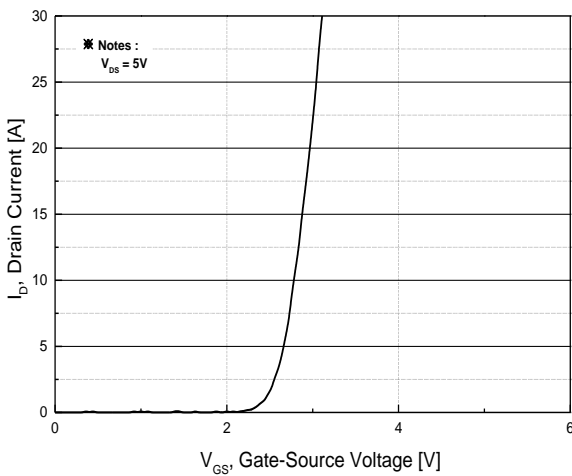
**Fig.2 On-Resistance Variation with Drain Current and Gate Voltage**



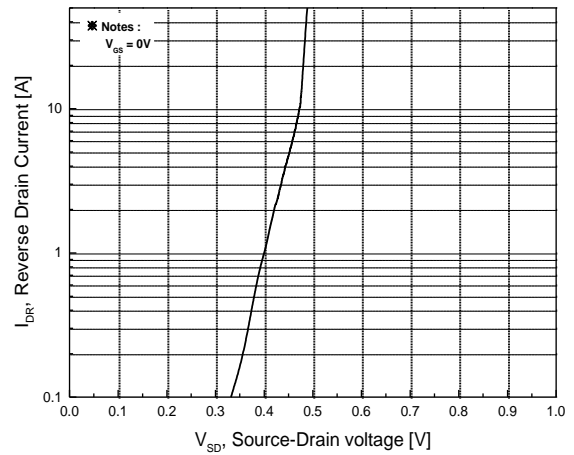
**Fig.3 On-Resistance Variation with Temperature**



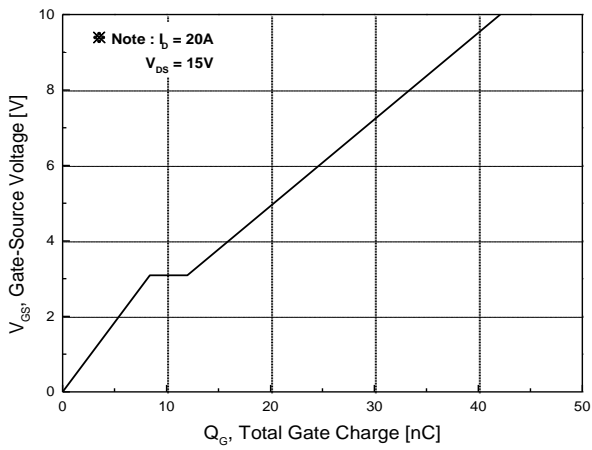
**Fig.4 On-Resistance Variation with Gate to Source Voltage**



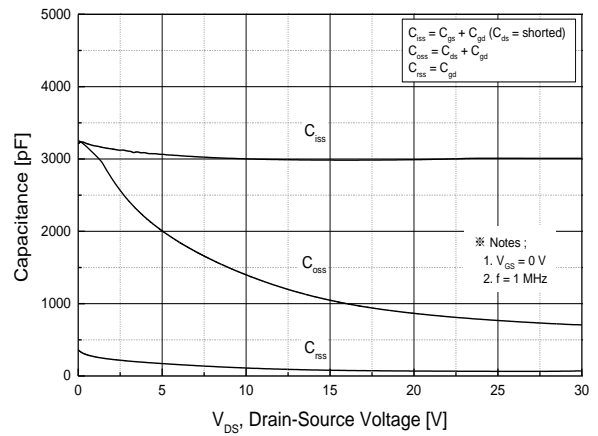
**Fig.5 Transfer Characteristics**



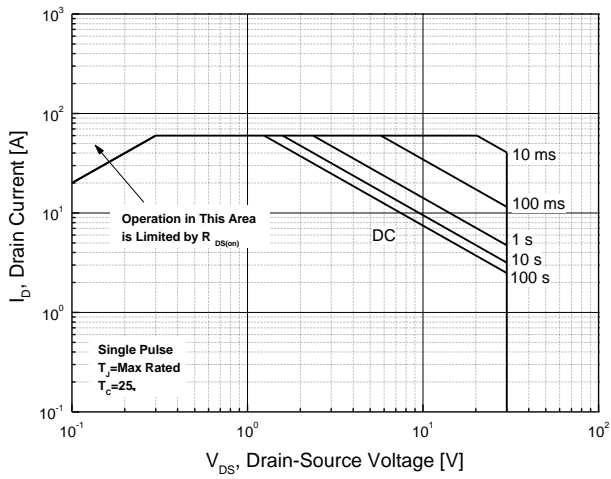
**Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature**



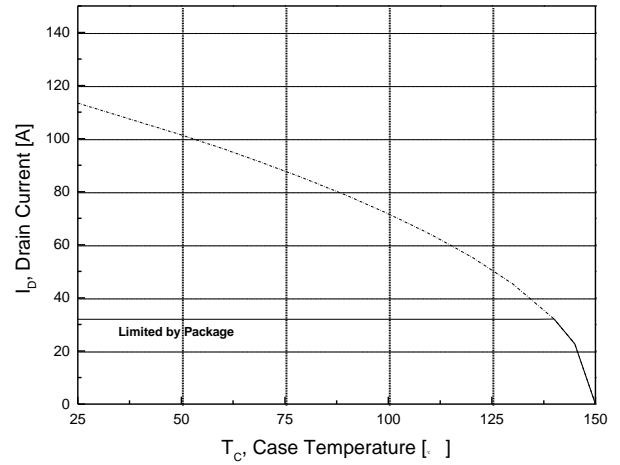
**Fig.7 Gate Charge Characteristics**



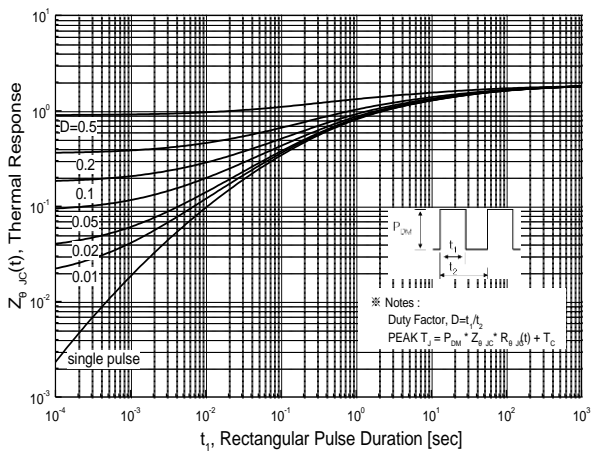
**Fig.8 Capacitance Characteristics**



**Fig.9 Maximum Safe Operating Area**



**Fig.10 Maximum Drain Current vs. Case Temperature**

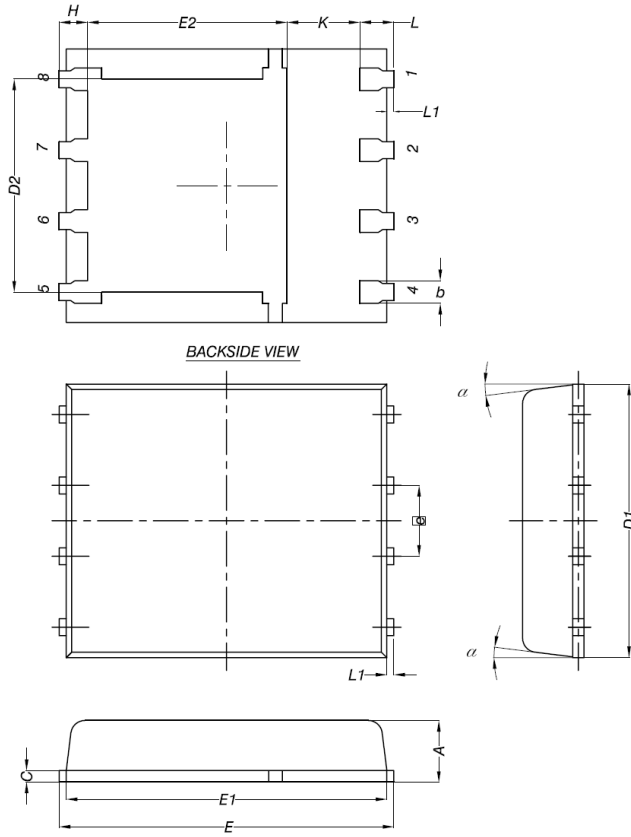


**Fig.11 Transient Thermal Response Curve**

**Package Dimension**

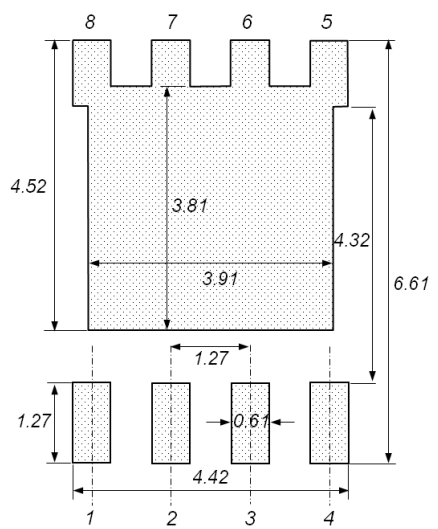
**PDFN56 (5x6mm)**

Dimensions are in millimeters, unless otherwise specified



Dimension	MILLIMETERS	
	Min	Max
A	0.90	1.10
b	0.33	0.51
C	0.20	0.34
D1	4.50	5.10
D2	-	4.22
E	5.90	6.30
E1	5.50	6.10
E2	-	4.30
e	1.27BSC	
H	0.41	0.71
K	0.20	-
L	0.51	0.71
α	0°	12°

**Land Pattern**



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